



# RF Power GaN Transistor

This 56 W asymmetrical Doherty RF power GaN transistor is designed for cellular base station applications requiring very wide instantaneous bandwidth capability covering the frequency range of 2496 to 2690 MHz.

This part is characterized and performance is guaranteed for applications operating in the 2496 to 2690 MHz band. There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

## 2600 MHz

- Typical Doherty Single-Carrier W-CDMA Characterization Performance:  $V_{DD} = 48 \text{ Vdc}$ ,  $I_{DQA} = 350 \text{ mA}$ ,  $V_{GSB} = -5.0 \text{ Vdc}$ ,  $P_{out} = 56 \text{ W Avg.}$ , Input Signal PAR = 9.9 dB @ 0.01% Probability on CCDF.<sup>(1)</sup>

Frequency	$G_{ps}$ (dB)	$\eta_D$ (%)	P3dB (dBm) <sup>(2)</sup>	ACPR (dBc)
2496 MHz	14.0	46.3	56.6	-35.4
2590 MHz	14.5	45.1	57.1	-36.6
2690 MHz	14.4	47.4	56.0	-33.2

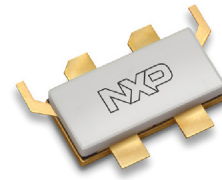
1. All data measured in fixture with device soldered to heatsink.
2. Data measured at pulsed CW, 10  $\mu\text{sec}(\text{on})$ , 10% duty cycle.

## Features

- High terminal impedances for optimal broadband performance
- Advanced high performance in-package Doherty
- Improved linearized error vector magnitude with next generation signal
- Able to withstand extremely high output VSWR and broadband operating conditions

## A3G26H501W17S

**2496–2690 MHz, 56 W AVG., 48 V  
 AIRFAST RF POWER GaN  
 TRANSISTOR**



NI-780S-4S2S

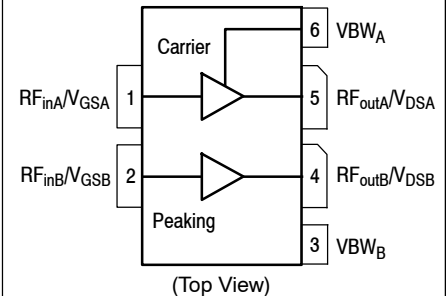


Figure 1. Pin Connections

**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	125	Vdc
Gate-Source Voltage	$V_{GS}$	-8, 0	Vdc
Operating Voltage	$V_{DD}$	0 to +55	Vdc
Maximum Forward Gate Current, $I_G$ (A+B), @ $T_C = 25^\circ\text{C}$	$I_{GMAX}$	66	mA
Storage Temperature Range	$T_{stg}$	-65 to +150	$^\circ\text{C}$
Case Operating Temperature Range	$T_C$	-55 to +150	$^\circ\text{C}$
Operating Active Die Surface Temperature Range	$T_J$	-55 to +225	$^\circ\text{C}$
Maximum Channel Temperature (1)	$T_{CH}$	275	$^\circ\text{C}$

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance by Infrared Measurement, Active Die Surface-to-Case Case Temperature $93^\circ\text{C}$ , $P_D = 80\text{ W}$	$R_{\theta JC}$ (IR)	0.90 (2)	$^\circ\text{C/W}$
Thermal Resistance by Finite Element Analysis, Channel-to-Case Case Temperature $90^\circ\text{C}$ , $P_D = 80\text{ W}$	$R_{\theta CHC}$ (FEA)	1.23 (3)	$^\circ\text{C/W}$

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JS-001-2017)	1C
Charge Device Model (per JS-002-2014)	C3

**Table 4. Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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**Off Characteristics (4)**

Drain-Source Breakdown Voltage ( $V_{GS} = -8\text{ Vdc}$ , $I_D = 24\text{ mAdc}$ ) ( $V_{GS} = -8\text{ Vdc}$ , $I_D = 42\text{ mAdc}$ )	$V_{(BR)DSS}$	150 150	—	—	Vdc
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**On Characteristics — Side A, Carrier**

Gate Threshold Voltage ( $V_{DS} = 10\text{ Vdc}$ , $I_D = 20\text{ mAdc}$ )	$V_{GS(th)}$	-3.5	-2.8	-2.3	Vdc
Gate Quiescent Voltage ( $V_{DD} = 48\text{ Vdc}$ , $I_{DA} = 350\text{ mAdc}$ , Measured in Functional Test)	$V_{GSA(Q)}$	-3.1	-2.7	-2.4	Vdc
Gate-Source Leakage Current ( $V_{DS} = 150\text{ Vdc}$ , $V_{GS} = -8\text{ Vdc}$ )	$I_{GSS}$	-9.9	—	—	mAdc

**On Characteristics — Side B, Peaking**

Gate Threshold Voltage ( $V_{DS} = 10\text{ Vdc}$ , $I_D = 20\text{ mAdc}$ )	$V_{GS(th)}$	-3.8	-3.3	-2.3	Vdc
Gate-Source Leakage Current ( $V_{DS} = 150\text{ Vdc}$ , $V_{GS} = -8\text{ Vdc}$ )	$I_{GSS}$	-9.9	—	—	mAdc

1. Reliability tests were conducted at  $225^\circ\text{C}$ . Operations with  $T_{CH}$  at  $275^\circ\text{C}$  will reduce median time to failure.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.nxp.com/RF> and search for AN1955.
3.  $R_{\theta CHC}$  (FEA) must be used for purposes related to reliability and limitations on maximum channel temperature. MTTF may be estimated by the expression  $MTTF$  (hours) =  $10^{[A + B/(T + 273)]}$ , where  $T$  is the channel temperature in degrees Celsius,  $A = -11.1$  and  $B = 8366$ .
4. Each side of device measured separately.

(continued)

**Table 4. Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>Functional Tests</b> <sup>(1)</sup> (In NXP Doherty Production Test Fixture, 50 ohm system) $V_{DD} = 48\text{ Vdc}$ , $I_{DQA} = 350\text{ mA}$ , $V_{GSB} = -5\text{ Vdc}$ , $P_{out} = 56\text{ W Avg.}$ , $f = 2690\text{ MHz}$ , Single-Carrier W-CDMA, IQ Magnitude Clipping, Input Signal PAR = 9.9 dB @ 0.01% Probability on CCDF. ACPR measured in 3.84 MHz Channel Bandwidth @ $\pm 5\text{ MHz}$ Offset. [See note on correct biasing sequence.]					
Power Gain	$G_{ps}$	12.7	13.7	15.7	dB
Drain Efficiency	$\eta_D$	35.5	40.7	—	%
$P_{out}$ @ 3 dB Compression Point, CW	P3dB	55.5	56.4	—	dBm
Adjacent Channel Power Ratio	ACPR	—	-33.2	-29.0	dBc

**Wideband Ruggedness** (In NXP Doherty Production Test Fixture, 50 ohm system)  $I_{DQA} = 350\text{ mA}$ ,  $V_{GSB} = -5\text{ Vdc}$ ,  $f = 2590\text{ MHz}$ , Additive White Gaussian Noise (AWGN) with 10 dB PAR

ISBW of 400 MHz at 55 Vdc, 194 W Avg. Modulated Output Power (8 dB Input Overdrive from 56 W Avg. Modulated Output Power)	No Device Degradation
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**Typical Performance** (In NXP Doherty Production Test Fixture, 50 ohm system)  $V_{DD} = 48\text{ Vdc}$ ,  $I_{DQA} = 350\text{ mA}$ ,  $V_{GSB} = -5\text{ Vdc}$ , 2496–2690 MHz Bandwidth

$P_{out}$ @ 3 dB Compression Point <sup>(2)</sup>	P3dB	—	500	—	W
AM/PM (Maximum value measured at the P3dB compression point across the 2496–2690 MHz bandwidth)	$\Phi$	—	-12	—	°
VBW Resonance Point (IMD Third Order Intermodulation Inflection Point)	$VBW_{res}$	—	160	—	MHz
Gain Flatness in 194 MHz Bandwidth @ $P_{out} = 56\text{ W Avg.}$	$G_F$	—	0.4	—	dB
Gain Variation over Temperature (-40°C to +85°C)	$\Delta G$	—	0.018	—	dB/°C
Output Power Variation over Temperature (-40°C to +85°C)	$\Delta P_{1dB}$	—	0.008	—	dB/°C

**Table 5. Ordering Information**

Device	Tape and Reel Information	Package
A3G26H501W17SR3	R3 Suffix = 250 Units, 44 mm Tape Width, 13-inch Reel	NI-780S-4S2S

- Part internally input matched.
- P3dB =  $P_{avg} + 7.0\text{ dB}$  where  $P_{avg}$  is the average output power measured using an unclipped W-CDMA single-carrier input signal where output PAR is compressed to 7.0 dB @ 0.01% probability on CCDF.

**NOTE: Correct Biasing Sequence for GaN Depletion Mode Transistors****Turning the device ON**

- Set  $V_{GS}$  to -5 V
- Turn on  $V_{DS}$  to nominal supply voltage (48 V)
- Increase  $V_{GS}$  until  $I_{DS}$  current is attained
- Apply RF input power to desired level

**Turning the device OFF**

- Turn RF power off
- Reduce  $V_{GS}$  down to -5 V
- Reduce  $V_{DS}$  down to 0 V (Adequate time must be allowed for  $V_{DS}$  to reduce to 0 V to prevent severe damage to device.)
- Turn off  $V_{GS}$

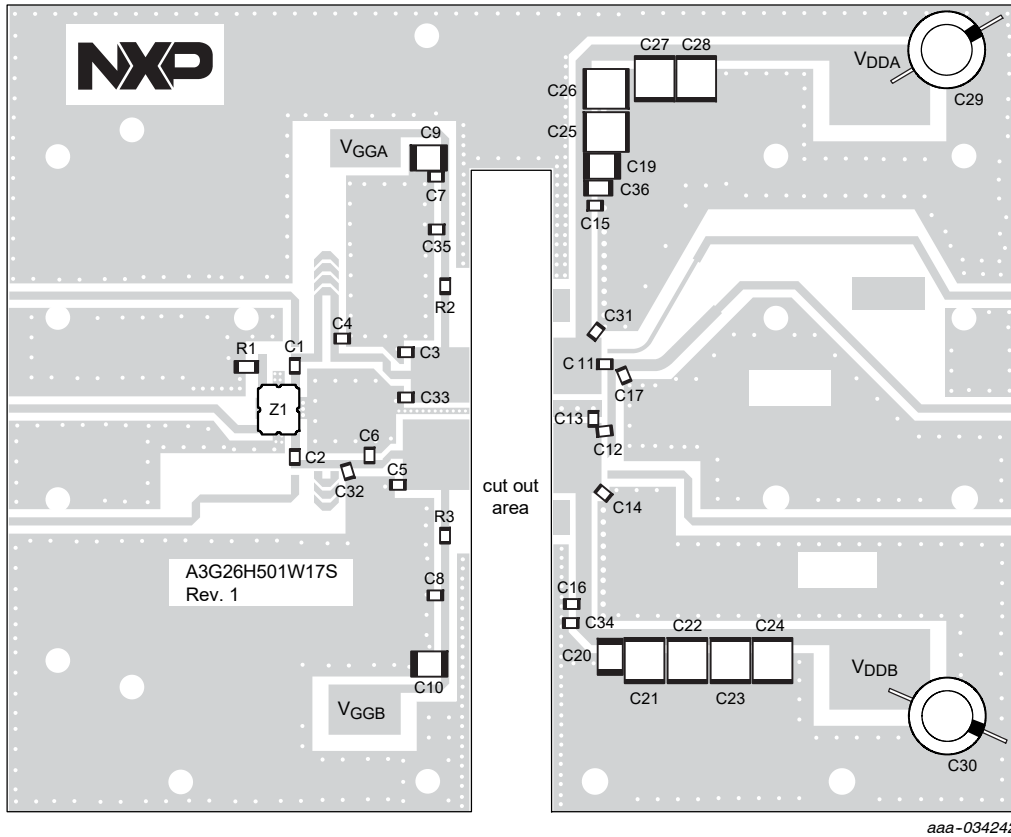


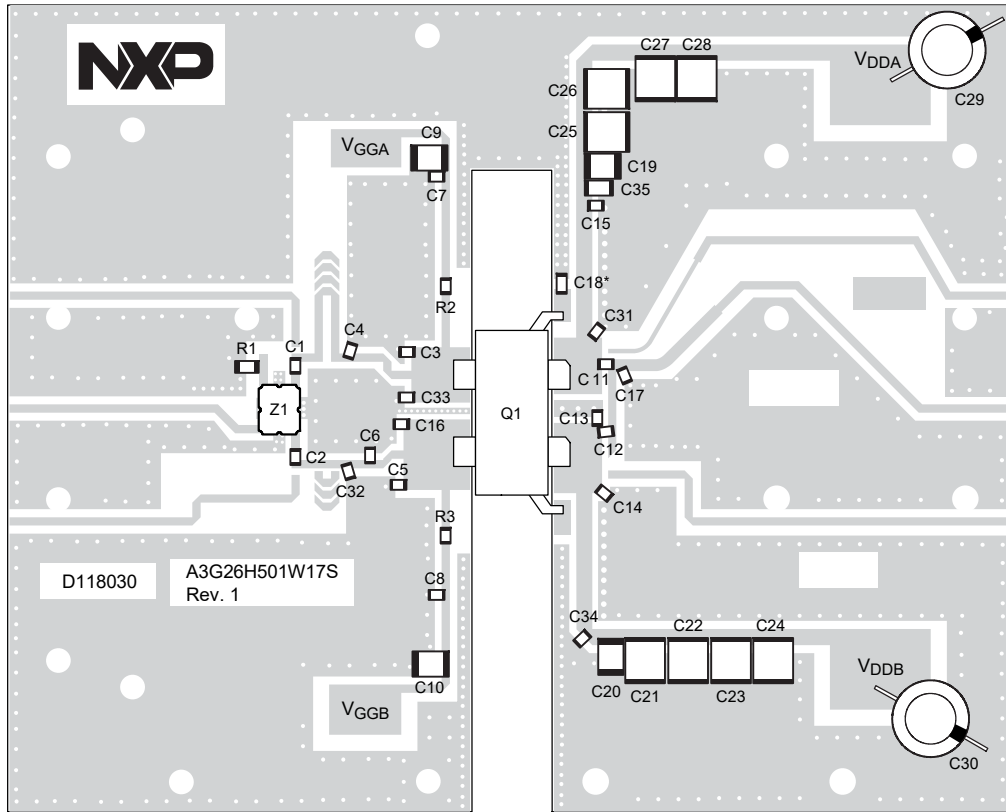
Figure 2. A3G26H501W17S Production Test Circuit Component Layout

Table 6. A3G26H501W17S Production Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
C1, C2, C7, C8, C15, C16, C35	6.8 pF Chip Capacitor	GQM2195C2E6R8BB12D	Murata
C3, C33	0.8 pF Chip Capacitor	GQM2195C2ER80BB12D	Murata
C4	1.2 pF Chip Capacitor	GQM2195C2E1R2BB12D	Murata
C5	1.6 pF Chip Capacitor	GQM2195C2E1R6BB12D	Murata
C6	1.5 pF Chip Capacitor	GQM2195C2E1R5BB12D	Murata
C9, C10	2.2 $\mu$ F Chip Capacitor	GRM31CR71H225KA88L	Murata
C11	3.9 pF Chip Capacitor	GQM2195C2E3R9BB12D	Murata
C12	2.2 pF Chip Capacitor	GQM2195C2E2R2BB12D	Murata
C13	0.6 pF Chip Capacitor	GQM2195C2ER60BB12D	Murata
C14	0.5 pF Chip Capacitor	GQM2195C2ER50BB12D	Murata
C17, C31	0.2 pF Chip Capacitor	GQM2195C2ER20BB12D	Murata
C19, C20	4.7 $\mu$ F Chip Capacitor	C4532X7S2A475M	TDK
C21, C22, C23, C24, C25, C26, C27, C28	15 $\mu$ F Chip Capacitor	C5750X7S2A156M	TDK
C29, C30	220 $\mu$ F, 100 V Electrolytic Capacitor	MCGPR100V227M16X26	Multicomp
C32	1.0 pF Chip Capacitor	GQM2195C2E1R0BB12D	Murata
C34	8.2 pF Chip Capacitor	GQM2195C2E8R2BB12D	Murata
C36	15 nF Chip Capacitor	C3225CH2A153J	TDK
R1	50 $\Omega$ , 8 W Termination Chip Resistor	C8A50Z4A	Anaren
R2, R3	3.3 $\Omega$ , 1/4 W Chip Resistor	CRCW08053R30JNEA	Vishay
Z1	2300–2700 MHz Band, 5 dB Directional Coupler	X3C25P1-05S	Anaren
PCB	Rogers RO3035, 0.020", $\epsilon_r = 3.6$	—	MTL

Note: Component number C18 is intentionally omitted.

### A3G26H501W17S



\*C18 is mounted vertically.

Note: All data measured in fixture with device soldered to heatsink.

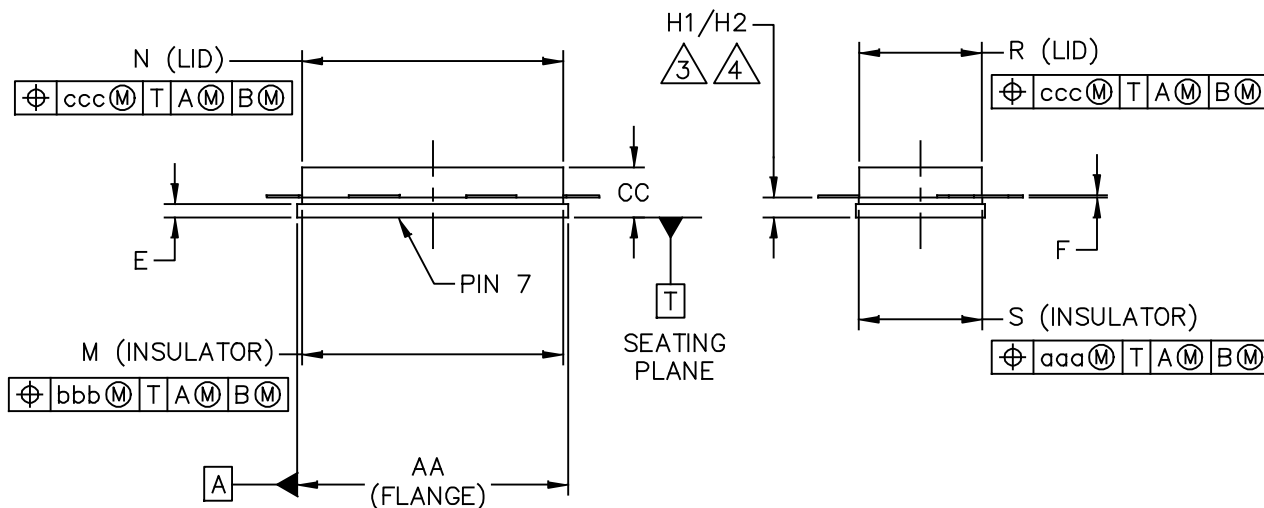
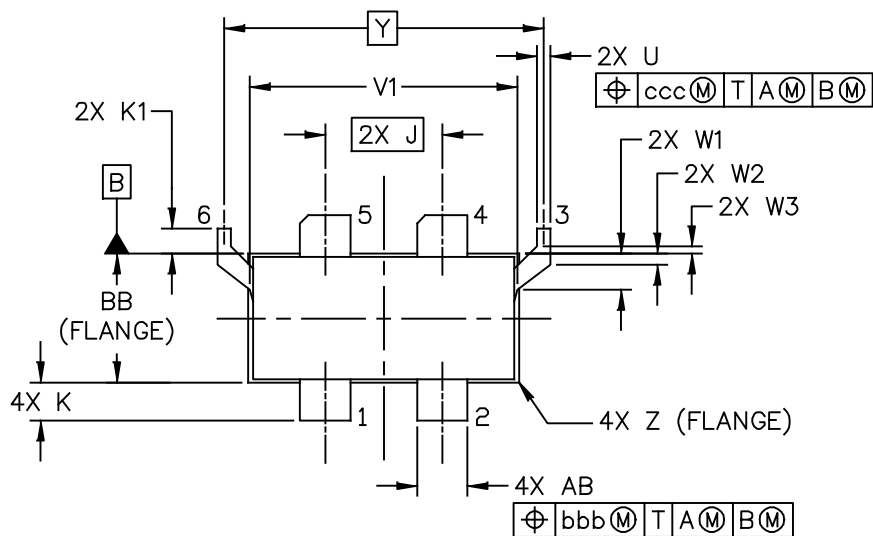
**Figure 3. A3G26H501W17S Characterization Test Circuit Component Layout**

**Table 7. A3G26H501W17S Characterization Test Circuit Component Designations and Values**

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C4	1.2 pF Chip Capacitor	GQM2195C2E1R2BB12D	Murata
C5	1.6 pF Chip Capacitor	GQM2195C2E1R6BB12D	Murata
C6	1.5 pF Chip Capacitor	GQM2195C2E1R5BB12D	Murata
C9, C10	2.2 $\mu$ F Chip Capacitor	GRM31CR71H225KA88L	Murata
C11	3.9 pF Chip Capacitor	GQM2195C2E3R9BB12D	Murata
C12	5.6 pF Chip Capacitor	GQM2195C2E2R2BB12D	Murata
C13	0.6 pF Chip Capacitor	GQM2195C2ER60BB12D	Murata
C14	0.5 pF Chip Capacitor	GQM2195C2ER50BB12D	Murata
C16	0.3 pF Chip Capacitor	GQM2195C2ER30BB12D	Murata
C17, C31	0.2 pF Chip Capacitor	GQM2195C2ER20BB12D	Murata
C18, C19, C20	4.7 $\mu$ F Chip Capacitor	C4532X7S2A475M	TDK
C21, C22, C23, C24, C25, C26, C27, C28	15 $\mu$ F Chip Capacitor	C5750X7S2A156M	TDK
C29, 30	220 $\mu$ F, 100 V Electrolytic Capacitor	MCGPR100V227M16X26	Multicomp
C32	1.0 pF Chip Capacitor	GQM2195C2E1R0BB12D	Murata
C34	8.2 pF Chip Capacitor	GQM2195C2E8R2BB12D	Murata
C35	15 nF Chip Capacitor	C3225CH2A153J	TDK
Q1	RF Power LDMOS Transistor	A3G26H501W17S	NXP
R1	50 $\Omega$ , 8 W Termination Chip Resistor	C8A50Z4A	Anaren
R2, R3	3.3 $\Omega$ , 1/4 W Chip Resistor	CRCW08053R30JNEA	Vishay
Z1	2300–2700 MHz Band, 5 dB Directional Coupler	X3C25P1-05S	Anaren
PCB	Rogers RO3035, 0.020", $\epsilon_r = 3.6$	D118030	MTL

**A3G26H501W17S**

### PACKAGE DIMENSIONS



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	SOT1799-6	14 AUG 2018

NOTES:

1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS H1 AND H2 ARE MEASURED .030 INCH (0.762 MM) AWAY FROM FLANGE PARALLEL TO DATUM B TO CLEAR EPOXY FLOW OUT. H1 APPLIES TO PINS 1, 2, 4 & 5. H2 APPLIES TO PINS 3 & 6.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	R	.365	.375	9.27	9.53
BB	.380	.390	9.65	9.91	S	.365	.375	9.27	9.53
CC	.125	.170	3.18	4.32	U	.035	.045	0.89	1.14
E	.035	.045	0.89	1.14	V1	.795	.805	20.19	20.45
F	.004	.007	0.10	0.18	W1	.0975	.1175	2.48	2.98
H1	.057	.067	1.45	1.70	W2	.0225	.0425	0.57	1.08
H2	.054	.070	1.37	1.78	W3	.0125	.0325	0.32	0.83
J	.350 BSC		8.89 BSC		Y	.956 BSC		24.28 BSC	
K	.0995	.1295	2.53	3.29	Z	R.000	R.040	R0.00	R1.02
K1	.070	.090	1.78	2.29	AB	.145	.155	3.68	3.94
M	.774	.786	19.66	19.96	aaa	.005		0.13	
N	.772	.788	19.61	20.02	bbb	.010		0.25	
					ccc	.015		0.38	

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## PRODUCT DOCUMENTATION, SOFTWARE AND TOOLS

Refer to the following resources to aid your design process.

### Application Notes

- AN1908: Solder Reflow Attach Method for High Power RF Devices in Air Cavity Packages
- AN1955: Thermal Measurement Methodology of RF Power Amplifiers

### Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

### Software

- .s2p File

### Development Tools

- Printed Circuit Boards

## REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	June 2019	<ul style="list-style-type: none"><li>• Initial release of data sheet</li></ul>
1	Aug. 2019	<ul style="list-style-type: none"><li>• Fig. 2, Production Test Circuit Component Layout: C18 component omitted, p. 4</li><li>• Table 6, Production Test Circuit Component Layout Parts List: C18 component omitted, updated the part number and description for R1, added note, p. 4</li><li>• Table 7, Characterization Component Layout Parts List: updated the part number and description for R1, p. 5</li></ul>



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